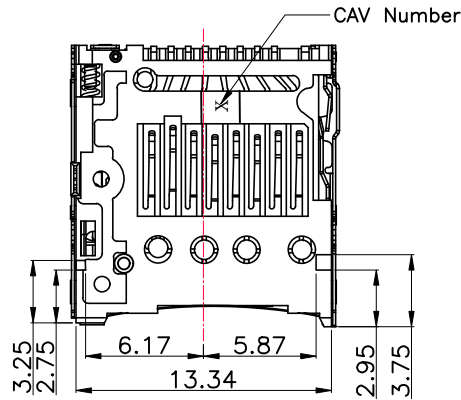
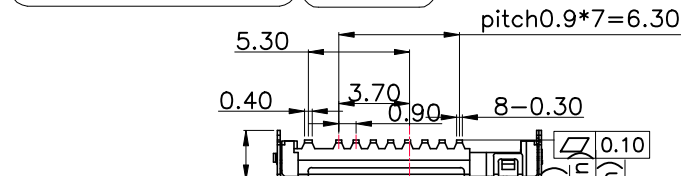


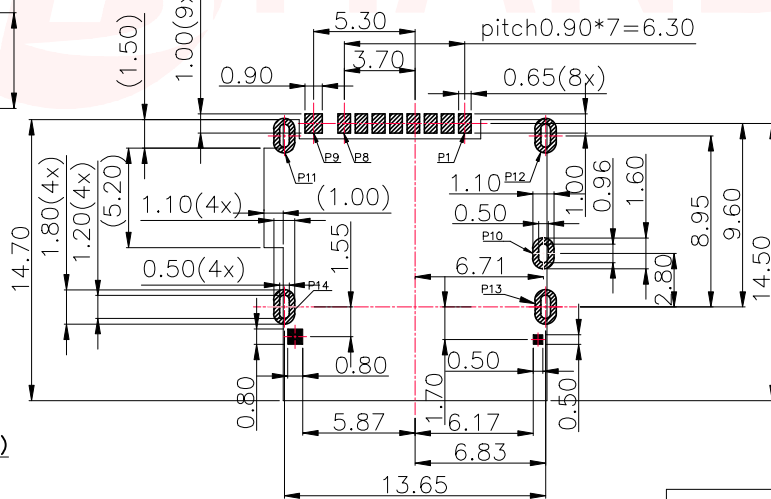
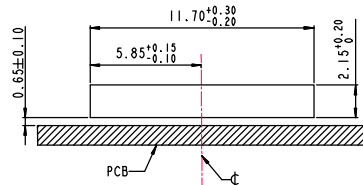
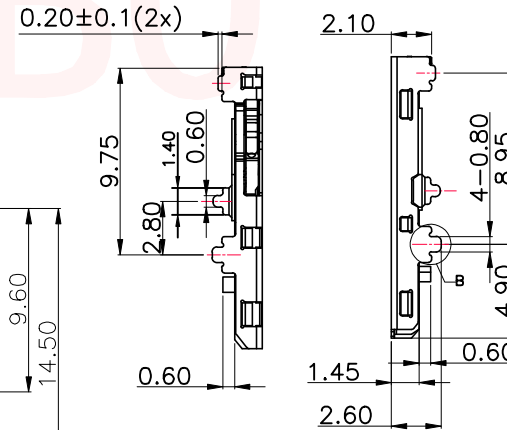
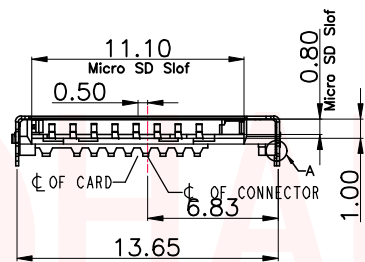
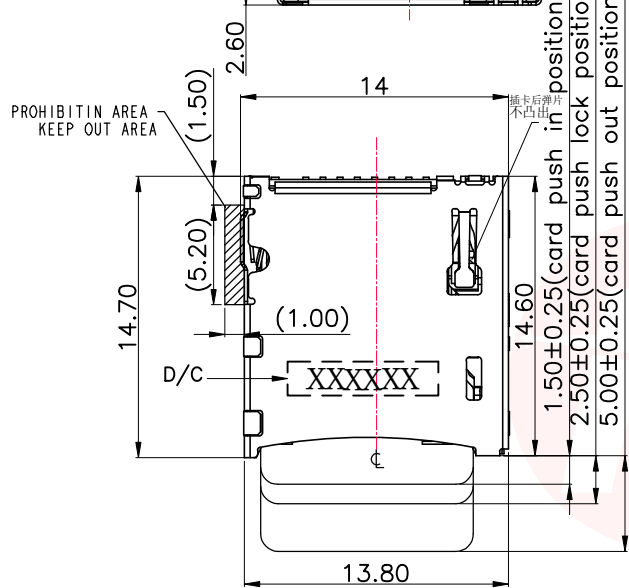


REV.	ECN NO OR DESCRIPTION	REVISED	DATE



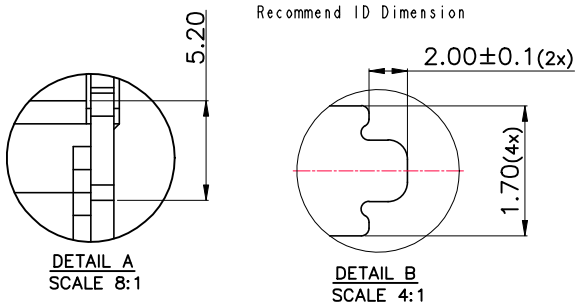
NOTES:

- MATERIAL:
 - 1-1.PLASTIC: LCP THERMOPLASTIC UL 94V-0 COLOR: BLACK.
 - 1-2.CONTACT:C5210R-SH T=0.15±0.01mm.
 - 1-3.SHELL: SUS304-H T=0.15±0.01mm.
 - 1-4.SPRING: SWP-B
- PLATING:
 - 2-1.CONTACT:
 - 2-1-1.CONTACT AREA: Au1-30u" PLATING OVER Ni30u".
 - 2-1-2.SOLDERTAIL AREA: Au1u" PLATING OVER Ni50u".
 - 2-2.SHELL:
 - 2-2-1.SOLDERABLE Ni50u" PLATING OVER ALL
- CONTACT AND TAIL COPLANARITY TO BE 0.10mm MAX
- RECOMMENDING A METAL MASK MORE THAN 0.15mm THICK, STENCILS AREA RELATIVE TO PAD AREA: LENGTH: 1.5 : 1 WIDTH: 1 : 1



PIN ASSIGNMENT

Pin No.	PIN ASSIGNMENT
P1	MICRO_SD_DAT2
P2	MICRO_SD_CD/DAT3
P3	MICRO_SD_CMD
P4	MICRO_SD_VDD
P5	MICRO_SD_CLK
P6	MICRO_SD_VSS
P7	MICRO_SD_DAT
P8	MICRO_SD_DAT
P9	MICRO_SD_CD
P10	GND
P11	GND
P12	GND
P13	GND
P14	GND



: PAD AREA
 : NO COMPONENT AREA
 : POINT GLUE

Recommended PCB LAYOUT TOP VIEW(TOLERANCE±0.05)

UNLESS OTHERWISE SPECIFIED TOLERANCES

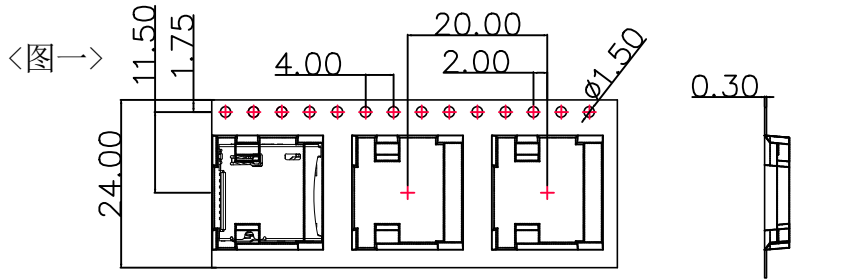
DECIMALS:	ANGLES:
X :±0.35	X :±2°
X.X :±0.25	X.X :±1°
X.XX :±0.15	

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 DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	MICRO SD 板LP/P 2.1H		
DWN	xiong	PART NO. MR-1202	
CHKD	lee	SCALE:1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET:1OF 1
REV: A4			
CUSTOMER COPY			



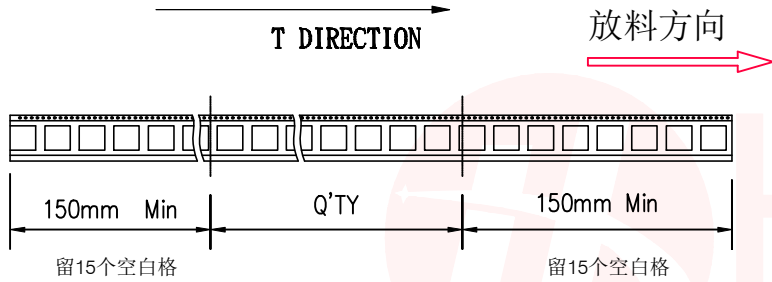
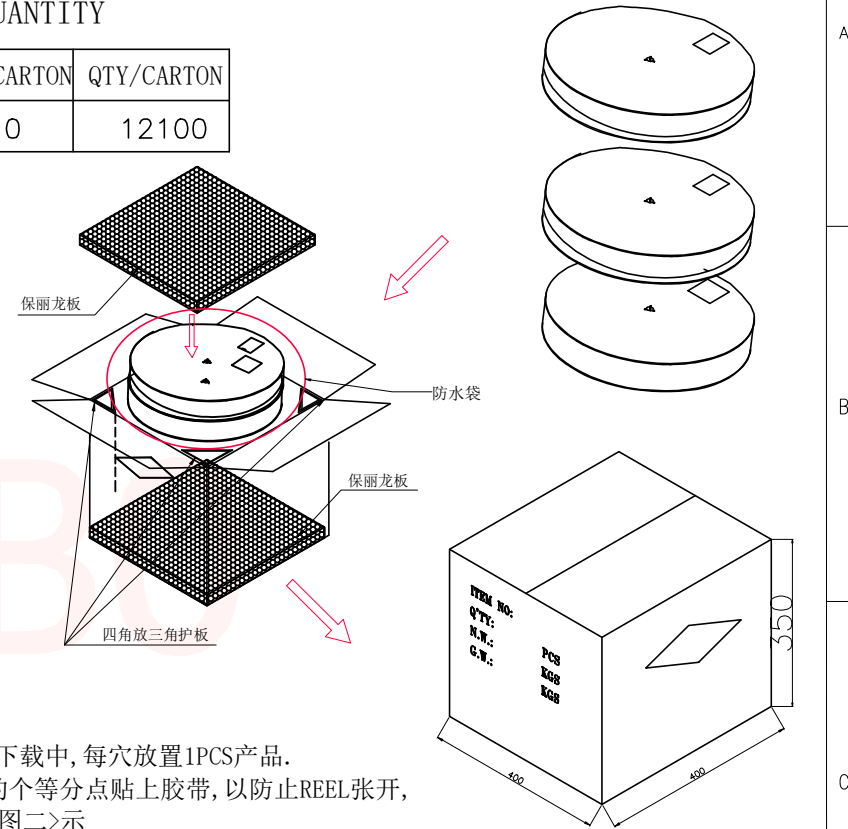
REV.	ECN NO OR DESCRIPTION	REVISED	DATE



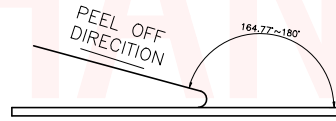
<TABLE 1> PACKAGING QUANTITY

QTY/REEL	REEL/CARTON	QTY/CARTON
1210	10	12100

<图三>



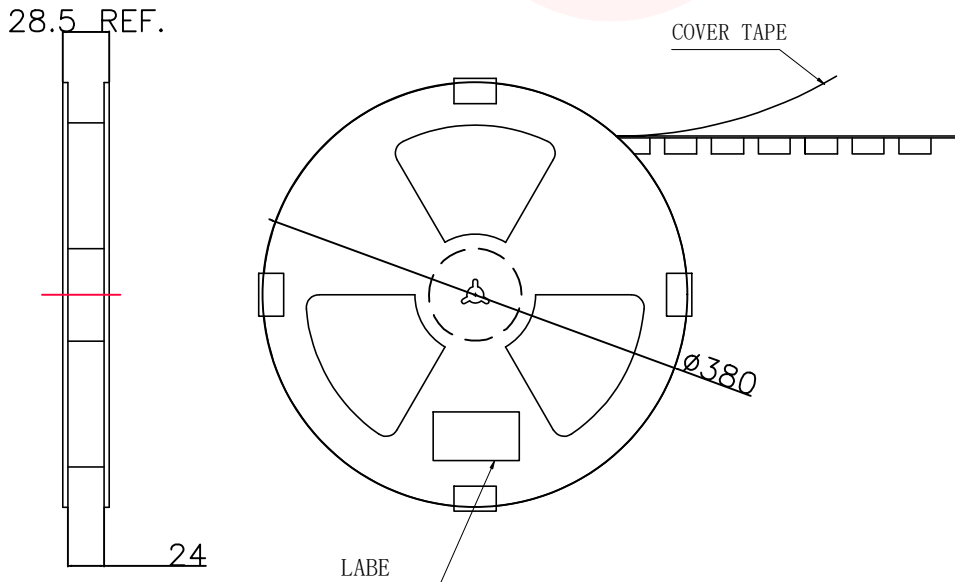
COVER TAPE PEELING FORCE: 20gf~100gf



NOTE:

- 依<图一>示放置产品于下载中, 每穴放置1PCS产品.
- 包装机包好后, 在REEL的个等分点贴上胶带, 以防止REEL张开, 每REEL贴1PCS标签, 如<图二>示
- 包装数量见如<TABLE 1>示
- 包装成箱见如<图三>示
箱底放保丽龙板, 再依次将指定数量的卷装产品用防水袋包好放入箱内, 四角分别放入四个三角护板, 最上层再放上保丽龙板.
- 封箱, 在封好的纸箱上按客户要求写上料号, 数量等

<图二>



UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD			
DECIMALS:	ANGLES:	TITLE MICRO SD 板上P/P 2.1H			
X : ±0.35	X : ±2°	DWN	xiong	PART NO. MR-1202	
X.X : ±0.25	X.X : ±1°	CHKD	lee	SCALE: 1:1	UNIT: mm
X.XX : ±0.15		APVD	wang	SIZE: A4	SHEET: 10F 1
CUSTOMER COPY					

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[2309923-1](#) [61126-050CAHLF](#) [IC1GA-68PD-1.27DS-EJ\(72\)](#) [GTFP08432B1HR](#) [SCE2MSDZN76A121SN](#) [10014744-011ALF](#) [10014744-](#)
[011LF](#) [10057542-1211FLF](#) [10067972-000LF](#) [10067972-050LF](#) [10122302-20110LF](#) [G85D1162022HHR](#) [MUP-C7809-1](#) [NANO SIM 7P](#)
[H1.37](#) [MICRO SIM 7P H1.35](#) [TF-CARD H1.8 SY](#) [MICRO SIM 6P H1.35](#) [TF-CARD H1.8](#) [TF-115Y-BCP9](#) [TF-115YY-ACP9](#) [SMN-309-](#)
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